

## CLAIMS

1. In a semiconductor-fabrication equipment of a minienviroment system wherein a wafer in a hermetic container is taken out into the semiconductor-fabrication equipment, and a processed wafer is put in the hermetic container, an clean-air injection device, which is connected to an air-supply device through an air-supply tube, is attached to the periphery of an opening of the semiconductor-fabrication equipment,

the clean-air injection device includes a filter means of cylindrically shaped filters connected to each other to be a rectangular frame; a filter case formed as a rectangular frame for encasing the filter means; and a guide cover formed with an injection slit and a guide slit in front of the filter case,

wherein an clean air is injected from the clean-air injection device to form an air curtain at a gap between an opening of a loading part attached to the semiconductor-fabrication equipment and a gateway of the hermetic container through which a wafer is taken out of or put in the hermetic container so as to prevent an ambient air from passing through the gap into the hermetic container when a lid of the hermetic container is opened to the semiconductor-fabrication equipment.

2. In a semiconductor-fabrication equipment of a minienviroment system wherein a wafer in a hermetic container is taken out into the semiconductor-fabrication equipment, and a processed wafer is put in the hermetic container, an clean-air injection device, which is connected to an air-supply device through an air-supply tube, is embedded in the periphery of an opening of the semiconductor-fabrication equipment,

the clean-air injection device includes a filter means of cylindrically shaped filters connected to each other to be a rectangular frame, the filter means being encased in a rectangular notch formed at the periphery of the opening; and a cover formed with an injection slit and a guide slit and secured to the notch,

wherein an clean air is injected from the clean-air injection device to form an air curtain at a gap between an opening

of a loading part attached to the semiconductor-fabrication equipment and a gateway of the hermetic container through which a wafer is taken out of or put in the hermetic container so as to prevent an ambient air from passing through the gap into the hermetic container when a lid of the hermetic container is opened to the semiconductor-fabrication equipment.

3. In a semiconductor-fabrication equipment of a minienviroment system wherein a wafer in a hermetic container is taken out into the semiconductor-fabrication equipment, and a processed wafer is put in the hermetic container, an clean-air injection device, which is connected to an air-supply device through an air-supply passage disposed in a front panel of the semiconductor-fabrication equipment, is embedded in the periphery of an opening of the semiconductor-fabrication equipment,

the clean-air injection device includes a filter means of cylindrically shaped filters connected to each other to be a rectangular frame, the filter means being encased in a rectangular notch formed at the periphery of the opening; and a cover formed with an injection slit and a guide slit and secured to the notch, wherein an clean air is injected from the clean-air injection device to form an air curtain at a gap between an opening of a loading part attached to the semiconductor-fabrication equipment and a gateway of the hermetic container through which a wafer is taken out of or put in the hermetic container so as to prevent an ambient air from passing through the gap into the hermetic container when a lid of the hermetic container is opened to the semiconductor-fabrication equipment.